

■ Features

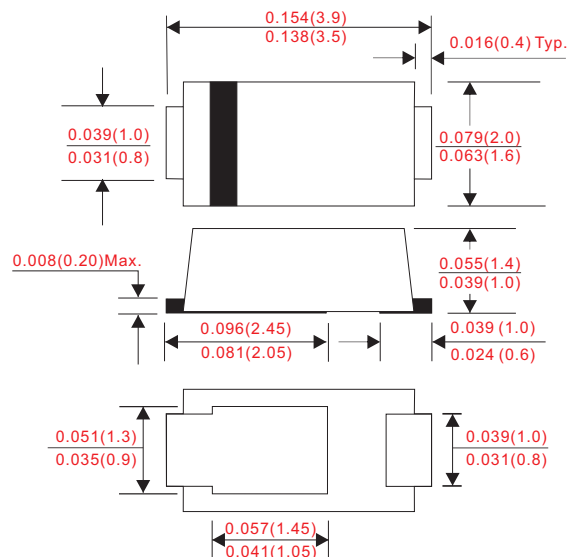
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- High surge capability.
- Ultrafast recovery time for high efficiency.
- Glass passivated chip junction.
- Suffix "G" indicates Halogen free parts, ex. BUGP4001WG-ST.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

■ Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123ST
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : Approximated 0.0155 gram

■ Outline

SOD-123ST



Dimensions in inches and (millimeters)

■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current		I_O			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}			30	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			5.0	uA
	$V_R = V_{RRM} \quad T_A = 125^\circ\text{C}$				100	
Storage temperature		T_{STG}	-55		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage V _{RRM} (V)	Max. RMS voltage V _{RMS} (V)	Max. DC blocking voltage V _R (V)	Max. forward voltage @1A, T _A = 25°C V _F (V)	Max. reverse recovery time(1) T _{rr} (ns)	Operating temperature T _J (°C)	
BUGP4001W-ST	H1	50	35	50	1.0	50	-55 ~ +150	
BUGP4002W-ST	H2	100	70	100				
BUGP4003W-ST	H3	200	140	200				
BUGP4004W-ST	H4	400	280	400	1.40	75		
BUGP4005W-ST	H5	600	420	600				
BUGP4006W-ST	H6	800	560	800				
BUGP4007W-ST	H7	1000	700	1000				

Note : 1. $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CHARACTERISTICS

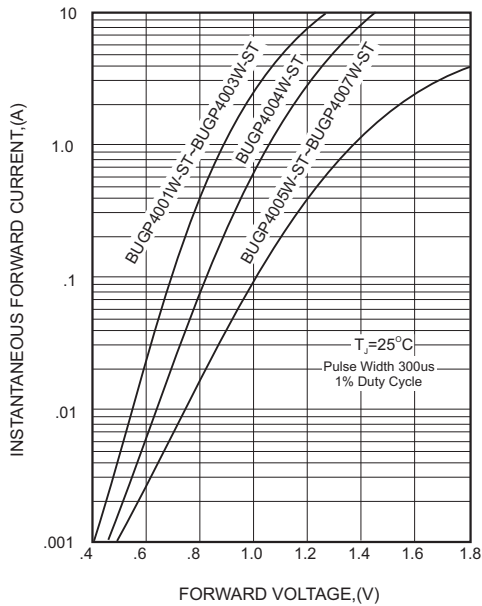


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

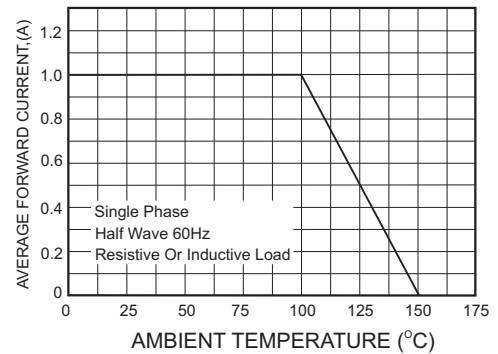


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

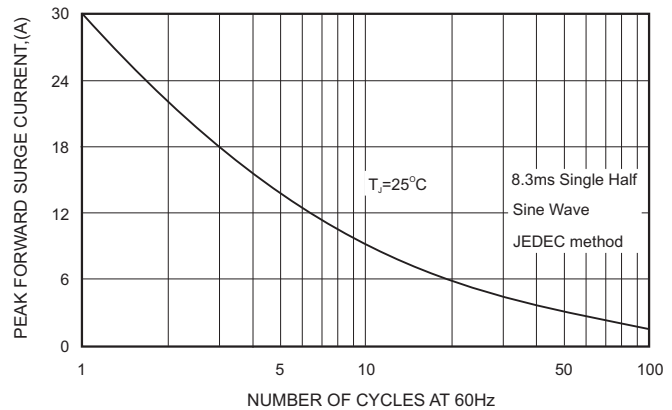
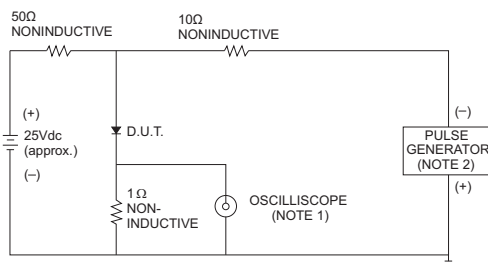


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

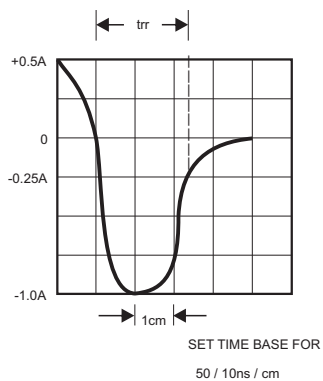
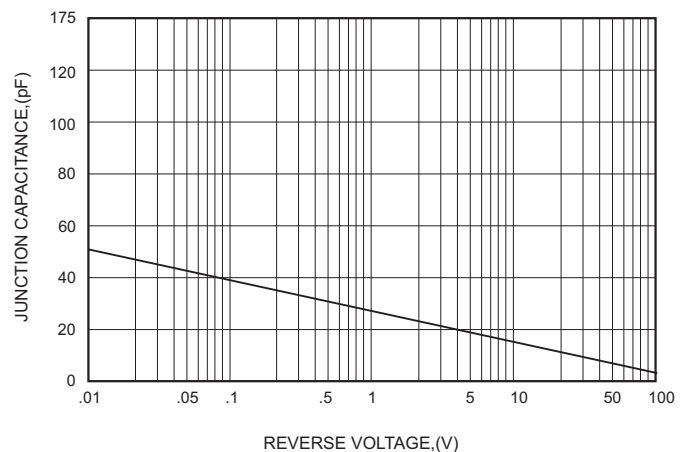
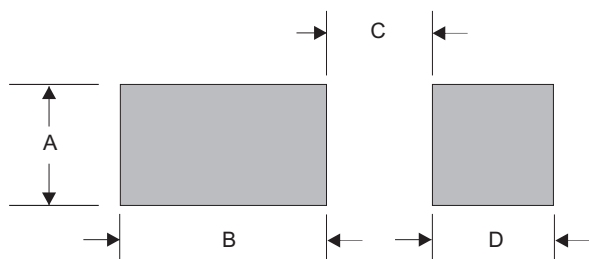


FIG.5-TYPICAL JUNCTION CAPACITANCE



■ SOD-123ST foot print



A	B	C	D
0.036 (0.90)	0.084 (2.10)	0.032 (0.80)	0.032 (0.80)

Dimensions in inches and (millimeters)

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